

BGS22WL10

Performance of DPDT (Dual-Pole /
Double-Throw) RF MOS switch

Broadband Differential LTE, WCDMA,
CDMA, UMTS Mobile Diversity
Applications

Application Note AN302

Revision: Rev. 1.0
2012-11-29

Edition 2013-06-26

**Published by
Infineon Technologies AG
81726 Munich, Germany**

**© 2013 Infineon Technologies AG
All Rights Reserved.**

LEGAL DISCLAIMER

THE INFORMATION GIVEN IN THIS APPLICATION NOTE IS GIVEN AS A HINT FOR THE IMPLEMENTATION OF THE INFINEON TECHNOLOGIES COMPONENT ONLY AND SHALL NOT BE REGARDED AS ANY DESCRIPTION OR WARRANTY OF A CERTAIN FUNCTIONALITY, CONDITION OR QUALITY OF THE INFINEON TECHNOLOGIES COMPONENT. THE RECIPIENT OF THIS APPLICATION NOTE MUST VERIFY ANY FUNCTION DESCRIBED HEREIN IN THE REAL APPLICATION. INFINEON TECHNOLOGIES HEREBY DISCLAIMS ANY AND ALL WARRANTIES AND LIABILITIES OF ANY KIND (INCLUDING WITHOUT LIMITATION WARRANTIES OF NON-INFRINGEMENT OF INTELLECTUAL PROPERTY RIGHTS OF ANY THIRD PARTY) WITH RESPECT TO ANY AND ALL INFORMATION GIVEN IN THIS APPLICATION NOTE.

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Application Note AN302

Revision History: 2012-11-29

Previous Revision: prev. Rev. x.x

Page	Subjects (major changes since last revision)

Trademarks of Infineon Technologies AG

A GOLD™, BlueMoon™, COMNEON™, CONVERGATE™, COSIC™, C166™, CROSSAVE™, CanPAK™, CIPOS™, CoolMOS™, CoolSET™, CONVERPATH™, CORECONTROL™, DAVE™, DUALFALC™, DUSLIC™, EasyPIM™, EconoBRIDGE™, EconoDUAL™, EconoPACK™, EconoPIM™, E GOLD™, EiceDRIVER™, EUPEC™, ELIC™, EPIC™, FALC™, FCOS™, FLEXISLIC™, GEMINAX™, GOLDMOS™, HITFET™, HybridPACK™, INCA™, ISAC™, ISOFACE™, IsoPACK™, IWORX™, M GOLD™, MIPAQ™, ModSTACK™, MUSLIC™, my d™, NovalithIC™, OCTALFALC™, OCTAT™, OmniTune™, OmniVia™, OptiMOS™, OPTIVERSE™, ORIGA™, PROFET™, PRO SIL™, PrimePACK™, QUADFALC™, RASIC™, ReverSave™, SatRIC™, SCEPTRE™, SCOUT™, S GOLD™, SensoNor™, SEROCCO™, SICOFI™, SIEGET™, SINDRION™, SLIC™, SMARTi™, SmartLEWIS™, SMINT™, SOCRATES™, TEMPFET™, thinQ!™, TrueENTRY™, TriCore™, TRENCHSTOP™, VINAX™, VINETIC™, VIONTIC™, WildPass™, X GOLD™, XMM™, X PMU™, XPOSYS™, XWAY™.

Other Trademarks

AMBA™, ARM™, MULTI ICE™, PRIMECELL™, REALVIEW™, THUMB™ of ARM Limited, UK. AUTOSAR™ is licensed by AUTOSAR development partnership. Bluetooth™ of Bluetooth SIG Inc. CAT iq™ of DECT Forum. COLOSSUS™, FirstGPS™ of Trimble Navigation Ltd. EMV™ of EMVCo, LLC (Visa Holdings Inc.). EPCOS™ of Epcos AG. FLEXGO™ of Microsoft Corporation. FlexRay™ is licensed by FlexRay Consortium. HYPERTERMINAL™ of Hilgraeve Incorporated. IEC™ of Commission Electrotechnique Internationale. IrDA™ of Infrared Data Association Corporation. ISO™ of INTERNATIONAL ORGANIZATION FOR STANDARDIZATION. MATLAB™ of MathWorks, Inc. MAXIM™ of Maxim Integrated Products, Inc. MICROTEC™, NUCLEUS™ of Mentor Graphics Corporation. Mifare™ of NXP. MIPI™ of MIPI Alliance, Inc. MIPS™ of MIPS Technologies, Inc., USA. muRata™ of MURATA MANUFACTURING CO. OmniVision™ of OmniVision Technologies, Inc. Openwave™ Openwave Systems Inc. RED HAT™ Red Hat, Inc. RFMD™ RF Micro Devices, Inc. SIRIUS™ of Sirius Sattelite Radio Inc. SOLARIS™ of Sun Microsystems, Inc. SPANSION™ of Spansion LLC Ltd. Symbian™ of Symbian Software Limited. TAIYO YUDEN™ of Taiyo Yuden Co. TEAKLITE™ of CEVA, Inc. TEKTRONIX™ of Tektronix Inc. TOKO™ of TOKO KABUSHIKI KAISHA TA. UNIX™ of X/Open Company Limited. VERILOG™, PALLADIUM™ of Cadence Design Systems, Inc. VLYNQ™ of Texas Instruments Incorporated. VXWORKS™, WIND RIVER™ of WIND RIVER SYSTEMS, INC. ZETEX™ of Diodes Zetex Limited.

Last Trademarks Update 2009 10 19

Table of Content

1	Introduction	6
2	Features	7
2.1	Main Features	7
2.2	Functional Diagram	7
2.3	Signal Description	8
3	Small Signal Characteristics Measurement Results	9
3.1	Insertion Loss	9
3.2	Return loss	10
3.3	Isolation of inactive paths	12
4	Switching time	14
4.1	Measurement Specifications	14
4.2	Measurement Setup	15
4.3	Measurement results	16
5	Intermodulation	17
5.1	Test conditions	17
5.2	Measurement Setup	18
5.3	Measurement results	19
6	Harmonic Generation	20
6.1	Measurement setup	20
6.2	Measurement results	21
6.2.1	Low Band (824 MHz)	21
6.2.2	High Band (1800 MHz)	22
7	Power Compression Measurements	23
8	Application Board and Measurement description	24
8.1	Application board	24
8.2	Measurement description and deembedding	25
Author	26	

List of Figures

Figure 1	Differential Band select Switching application	6
Figure 2	Functional Diagram	7
Figure 3	Pin configuration of BGS22WL10	8
Figure 4	Forward Transmission curves for all RF paths	9
Figure 5	Return loss for active port 2 (2P/2N).....	10
Figure 6	Return loss for active port 3 (3P/3N).....	11
Figure 7	Isolation of Port 3 (3P/3N) by active Port 2 (2P/2N)	12
Figure 8	Isolation of Port 2 (2P/2N) by active Port 3 (3P/3N)	13
Figure 9	Switching Time	14
Figure 10	Rise/Fall Time	14
Figure 11	Switching Time Measurement Setup	15
Figure 12	Switching Time of BGS22WL10	16
Figure 13	Block diagram of RF Switch intermodulation	17
Figure 14	Test set-up for IMD Measurements.....	18
Figure 15	Set-up for harmonics measurement.....	20
Figure 16	2 nd harmonic at $f_c=824$ MHz	21
Figure 17	3 rd harmonic at $f_c=824$ MHz.....	21
Figure 18	2 nd harmonic at $f_c=1800$ MHz	22
Figure 19	3 rd harmonic at $f_c=1800$ MHz.....	22
Figure 20	Power Compression Measurement Results at $f_c=824$ MHz.....	23
Figure 21	BGS22WL10 application board.....	24
Figure 22	Layout of the application board and deembedding kit	24
Figure 23	PCB layer information	24
Figure 24	SMA connector for deembedding procedure	25

List of Tables

Table 1	Device description	6
Table 2	Pin Description (top view)	8
Table 3	Truth table	8
Table 4	Insertion Loss of throw between port1 (1P/1N) and port2 (2P/2N).....	10
Table 5	Insertion Loss of throw between port1 (1P/1N) and port3 (3P/3N).....	10
Table 6	Return loss of active ports.....	11
Table 7	Isolation of Port3 (3P/3N) bby active port 2 (2P/2N).....	12
Table 8	Isolation of Port2 (2P/2N) bby active port 3 (3P/3N).....	13
Table 9	Switching time measurement results of BGS22WL10	16
Table 10	Test conditions and specifications of IMD measurements.....	17
Table 11	IMD products of Band I	19
Table 12	IMD products of Band V	19

1 Introduction

The BGS22WL10 RF MOS switch is specifically designed for differential diversity applications (e.g. [Figure 1](#)) in low bands up to 3 GHz like 3G WCDMA diversity, CDMA diversity, UMTS diversity or LTE diversity RF frontend system solutions. Therefore, the Insertion loss of the BGS22WL10 below 2 GHz is closed to 0.35 dB, upto 3 GHz the IL is in the range of 0.45 dB and the port to port Isolation is more than 26 dB. A typical application is to combine two Rx paths in a mobile cellular device after the Rx filters or duplexers into one input to the transceiver IC. The IC can also be used for a wide variety of applications switching balanced signals in a frequency range of 0.1 - 3 GHz.

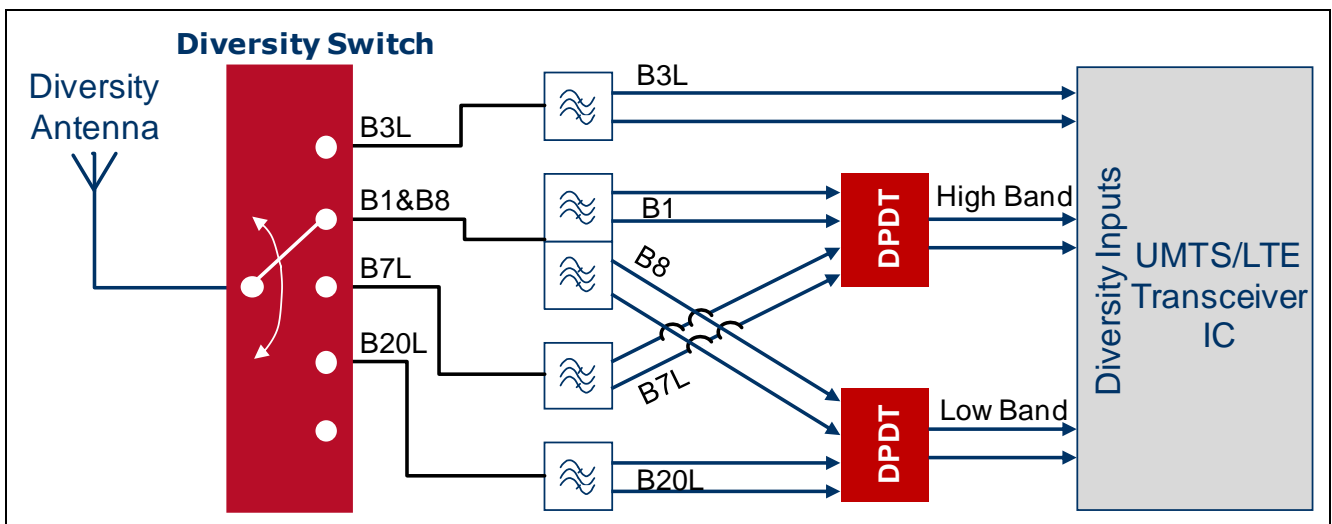


Figure 1 Differential Band select Switching application

Unlike GaAs technology, external DC blocking capacitors at the RF Ports are only required if DC voltage is applied externally. The BGS22WL10 RF Switch is manufactured in Infineon's patented MOS technology, offering the performance of GaAs with the economy and integration of conventional CMOS including the inherent higher ESD robustness. This DPDT (Dual-Pole / Double Throw) RF MOS switch which combines two differential signals into one differential output or splits one differential signal into two separate differential lines. The parallel paths of the switch are controlled simultaneously through the same signals. The switch is designed to operate in battery powered applications with a supply voltage range of 2.4 - 3.6 V while the current consumption is below 300 μ A. The highly symmetric design ensures best phase- and amplitude accuracy.

The RF switch is packaged in a standard RoHS compliant TSLP-10-1 package with a small outline of only 1.55 x 1.15 mm².

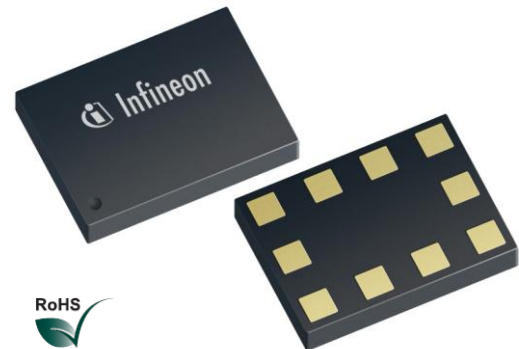
Table 1 Device description

Product Name	Product Type	Package	Marking
BGS22WL10	DPDT RF Switch	TSLP-10-1	W2

2 Features

2.1 Main Features

- DPDT (Dual-Pole / Double-Throw) differential RF switch
- All ports fully symmetrical
- High ESD robustness
- Frequency range: 0.1 - 3 GHz
- High signal power up to 30 dBm
- Extremely low insertin loss
- High port-to-port-isolation
- Supply voltage 2.4 - 3.6 V
- No decoupling capacitors required if no DC applied on RF lines
- Lead and halogen free package (RoHS and WEEE compliant)
- Small leadless package TSLP-10-1 with the size of 1.55 x 1.15 mm² and a maximum height of 0.77 mm.



2.2 Functional Diagram

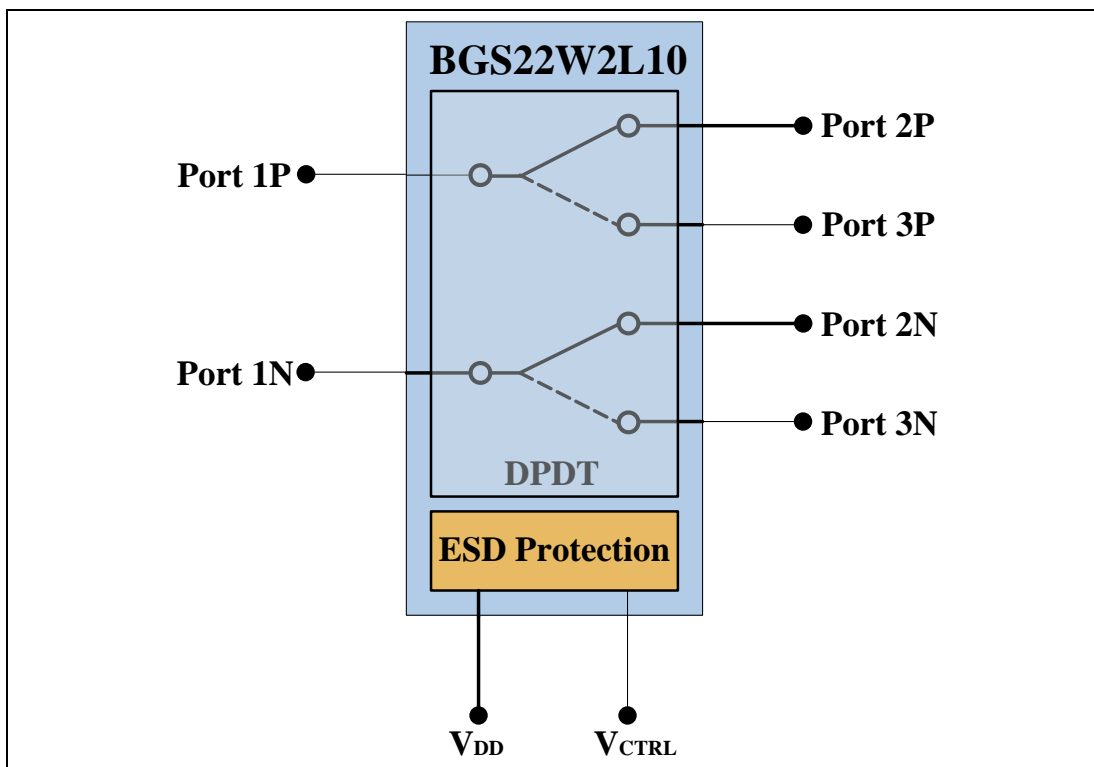


Figure 2 Functional Diagram

2.3 Signal Description

Table 2 Pin Description (top view)

Pin NO	Name	Pin Type	Function
1	Port 3P	I/O	RF port 3P
2	GND	GND	Ground
3	GND	GND	Ground
4	Port 2N	I/O	RF port 2N
5	Port 2P	I/O	RF port 2P
6	CTRL	I	Control Pin
7	Port 1P	I/O	RF port 1P
8	Port 1N	I/O	RF port 1N
9	VDD	Supply	Supply voltage
10	CTRL	I	Control Pin

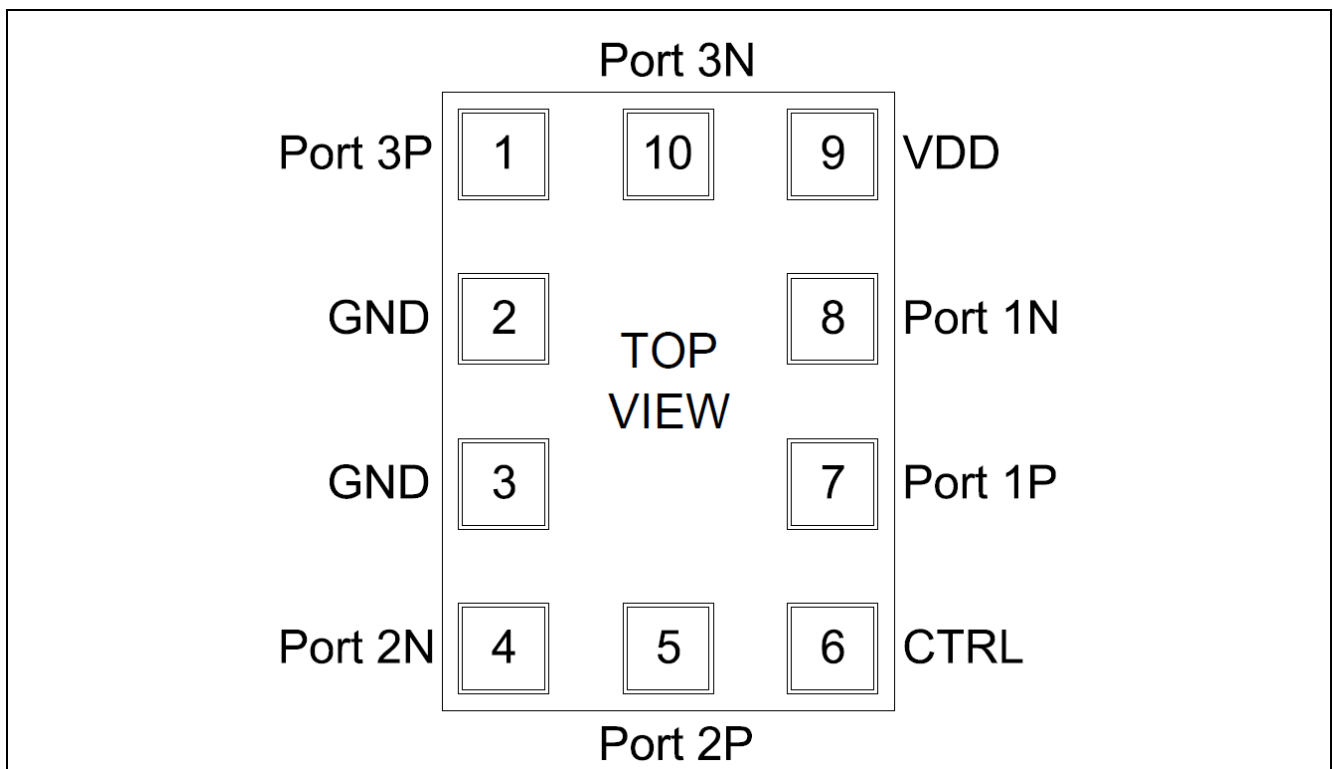


Figure 3 Pin configuration of BGS22WL10

Table 3 Truth table

Pin No.	Control
Port1 to Port2	0
Port1 to Port3	1

3 Small Signal Characteristics Measurement Results

All measurement results of this application note are measured with a typical device of the BGS22WL10 on an application board. The measurement procedure is shown in [chapter 8](#) including the needed deembedding.

The small signal characteristics are measured at 25 °C, 0 dBm Pin, 3 Volt Vdd, 3 V Vcrlt up to 10 GHz with a Network analyzer connected to an automatic multiport switch box in single ended mode. A differential simulation is possible by using an ideal transformer in between the Port 1P to 1N, 2P to 2N and 3P to 3N thanks to the full s-Parameter matrix of the BGS22WL10 which is provided @ Infineon's internet page.

In the following tables and graphs the most important RF parameter of the BGS22WL10 are shown. The markers are set to the most important frequencies of the WCDMA system.

3.1 Insertion Loss

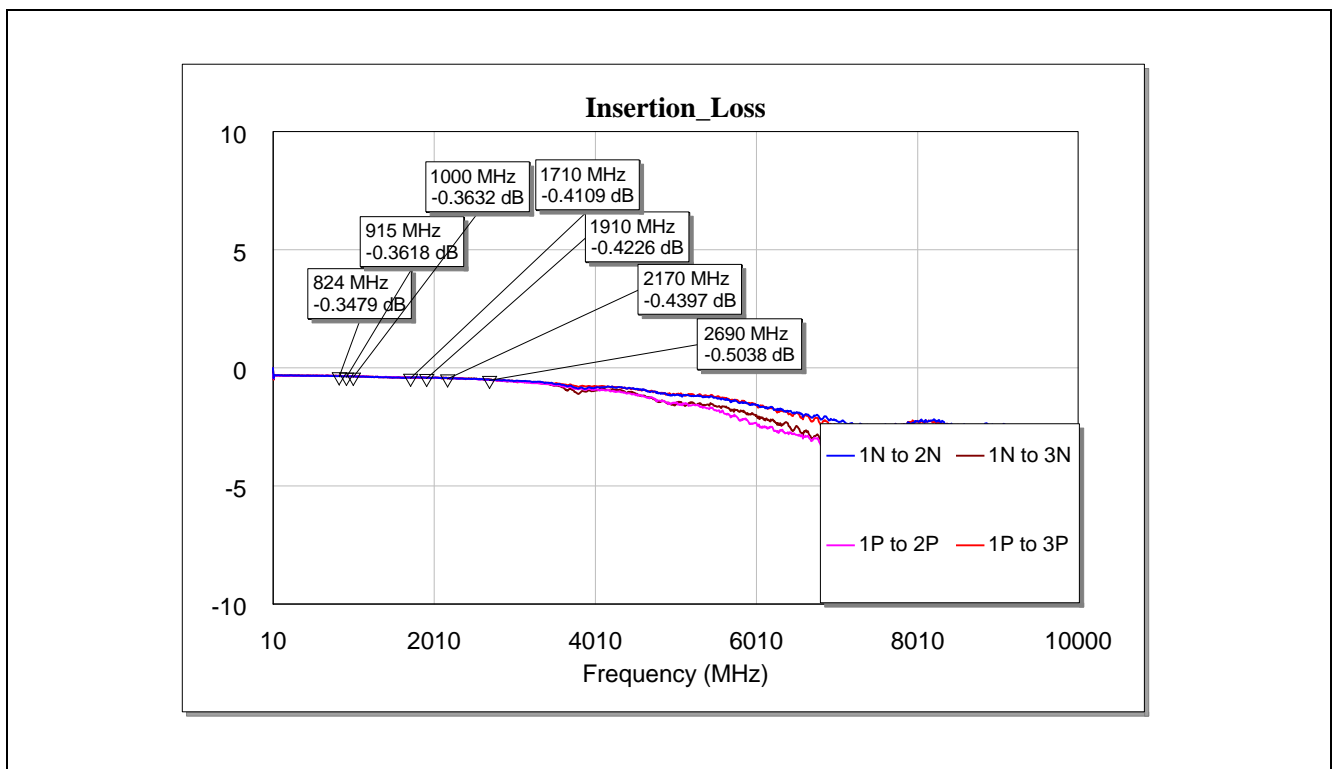


Figure 4 Forward Transmission curves for all RF paths

Table 4 Insertion Loss of throw between port1 (1P/1N) and port2 (2P/2N)

Frequency (MHz)	824	915	1000	1710	1910	2170	2690
RF path							
1P → 2P	0.35	0.36	0.36	0.41	0.42	0.44	0.5
1N → 2N	0.34	0.35	0.35	0.41	0.42	0.44	0.52

Table 5 Insertion Loss of throw between port1 (1P/1N) and port3 (3P/3N)

Frequency (MHz)	824	915	1000	1710	1910	2170	2690
RF path							
1P → 3P	0.34	0.35	0.36	0.41	0.41	0.43	0.5
1N → 3N	0.34	0.36	0.36	0.42	0.43	0.44	0.5

3.2 Return loss

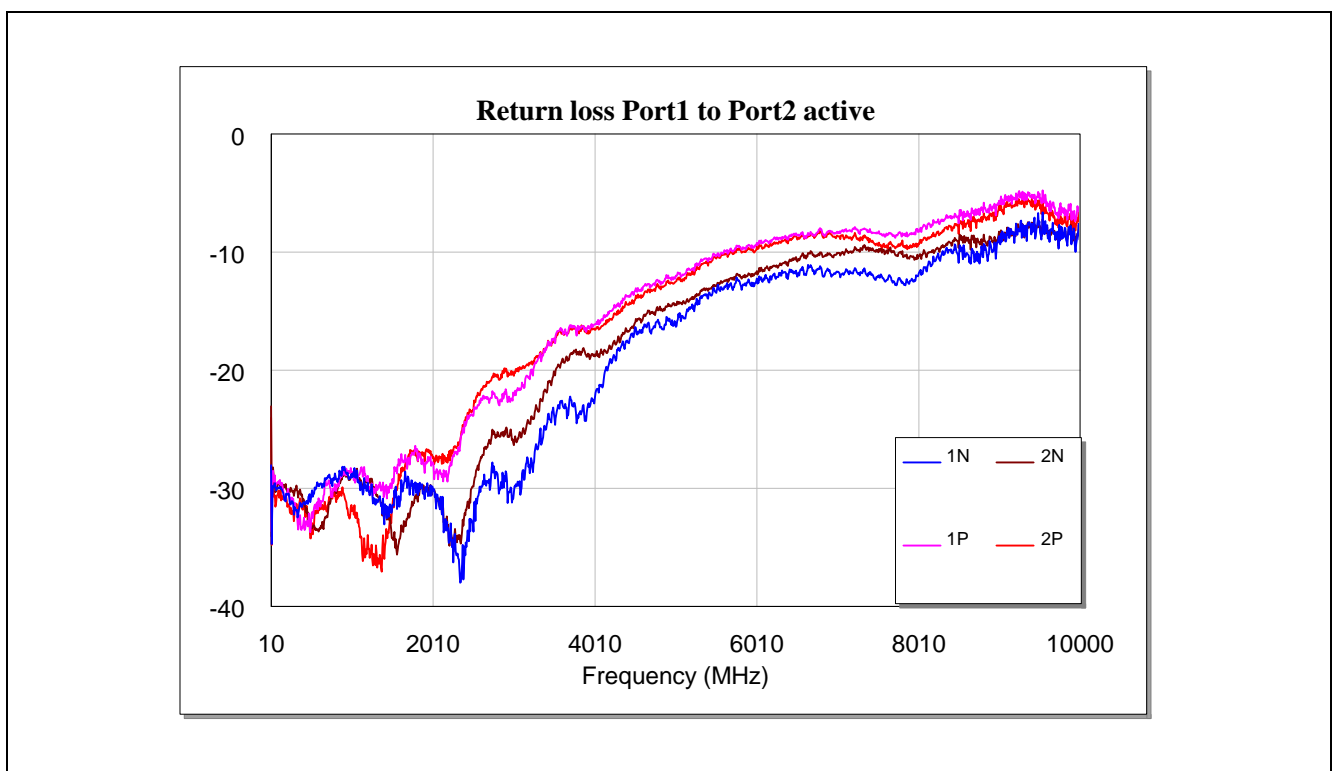


Figure 5 Return loss for active port 2 (2P/2N)

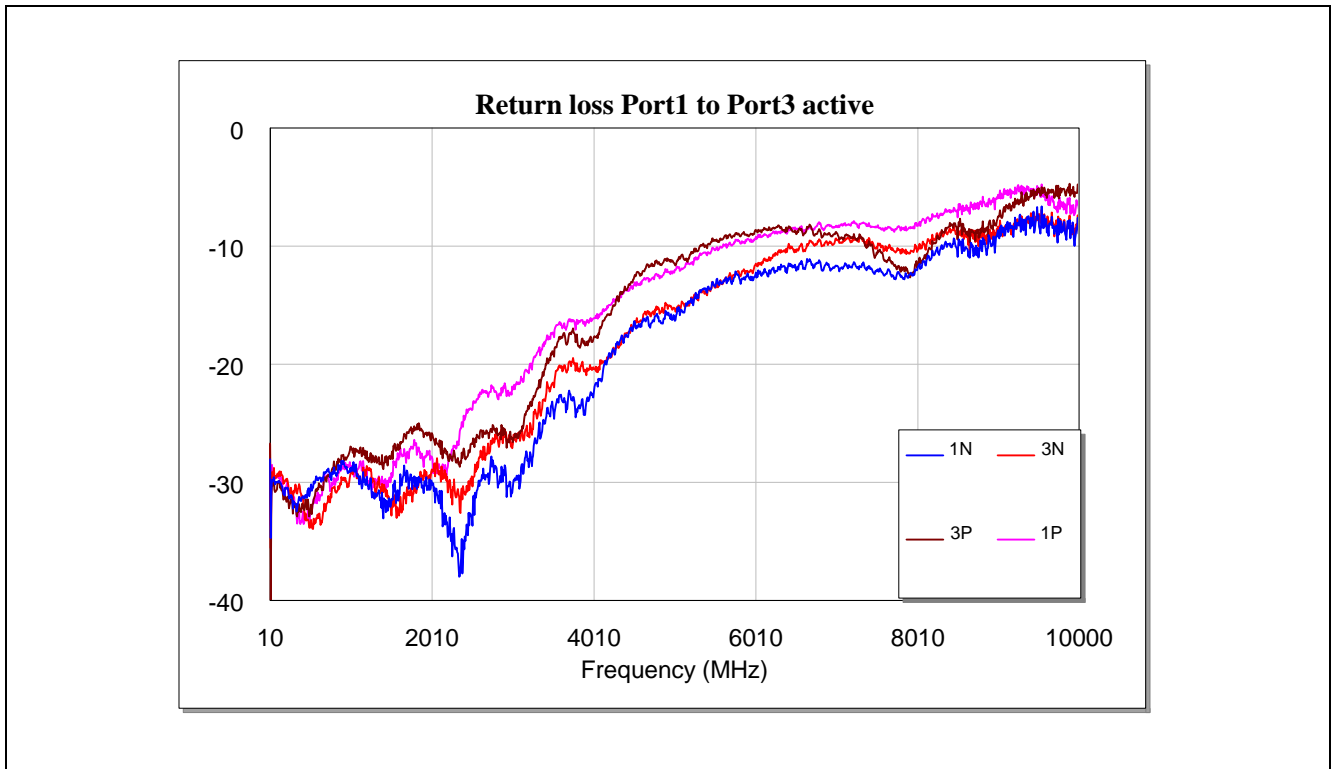


Figure 6 Return loss for active port 3 (3P/3N)

Table 6 Return loss of active ports

Frequency (MHz)	port	824	915	1000	1710	1910	2170	2690
Throw port 1 to port 2	1P	-29.4	-28.2	-28.8	-29.5	-30.5	-33.3	-29.4
	1N	-29.8	-28.6	-28.6	-27.6	-28.3	-28.6	-22.4
	2P	-30.2	-28.9	-29	-32.4	-30.2	-33.1	-26.2
	2N	-30.7	-30.7	-31.4	-27.1	-27.4	-27.7	-21
Throw port 1 to port 3	1P	-29.2	-28.7	-23.2	-24.4	-22.5	-28.9	-25.8
	1N	-32.7	-37.6	-31.6	-32.4	-26.6	-23.9	-31.5
	3P	-28.9	-27.7	-27	-25.8	-26	-27.3	-25.8
	3N	-30.9	-29.8	-29.3	-31	-29.3	-29.5	-27.5

3.3 Isolation of inactive paths

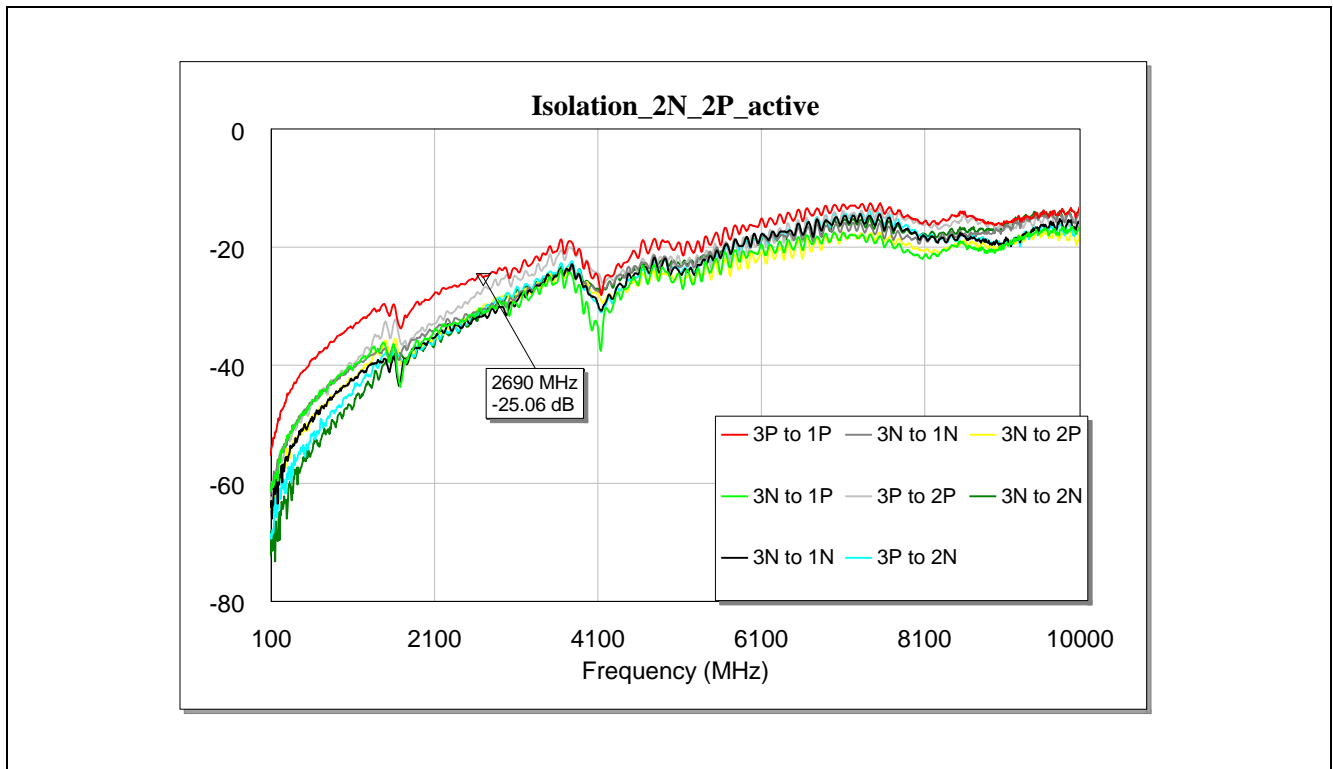


Figure 7 Isolation of Port 3 (3P/3N) by active Port 2 (2P/2N)

Table 7 Isolation of Port3 (3P/3N) bby active port 2 (2P/2N)

Port to port isolation	824	915	1000	1710	1910	2170	2690
3P → 1P	-36	-35	-34.3	-33.1	-29.6	-27.7	-25.1
3N → 1P	-42.8	-41.8	-41.2	-41.4	-36.6	-34.1	-31.2
3P → 1N	-45.6	-44.6	-43.6	-40.1	-37.1	-34.1	-31.7
3N → 1N	-43.3	-42.2	-41.6	-37.3	-35.3	-33.2	-30.6
3P → 2P	-42.8	-42.2	-41.4	-36.5	-34.3	-31.7	-27.2
3P → 2N	-48.1	-46.9	-45.6	-39.4	-36.8	-35.6	-31
3N → 2P	-45.3	-44.4	-43.8	-39.8	-37.1	-34.6	-30.1
3N → 2N	-50.6	-48.7	-47.5	-38.6	-36.6	-35.9	-31.5

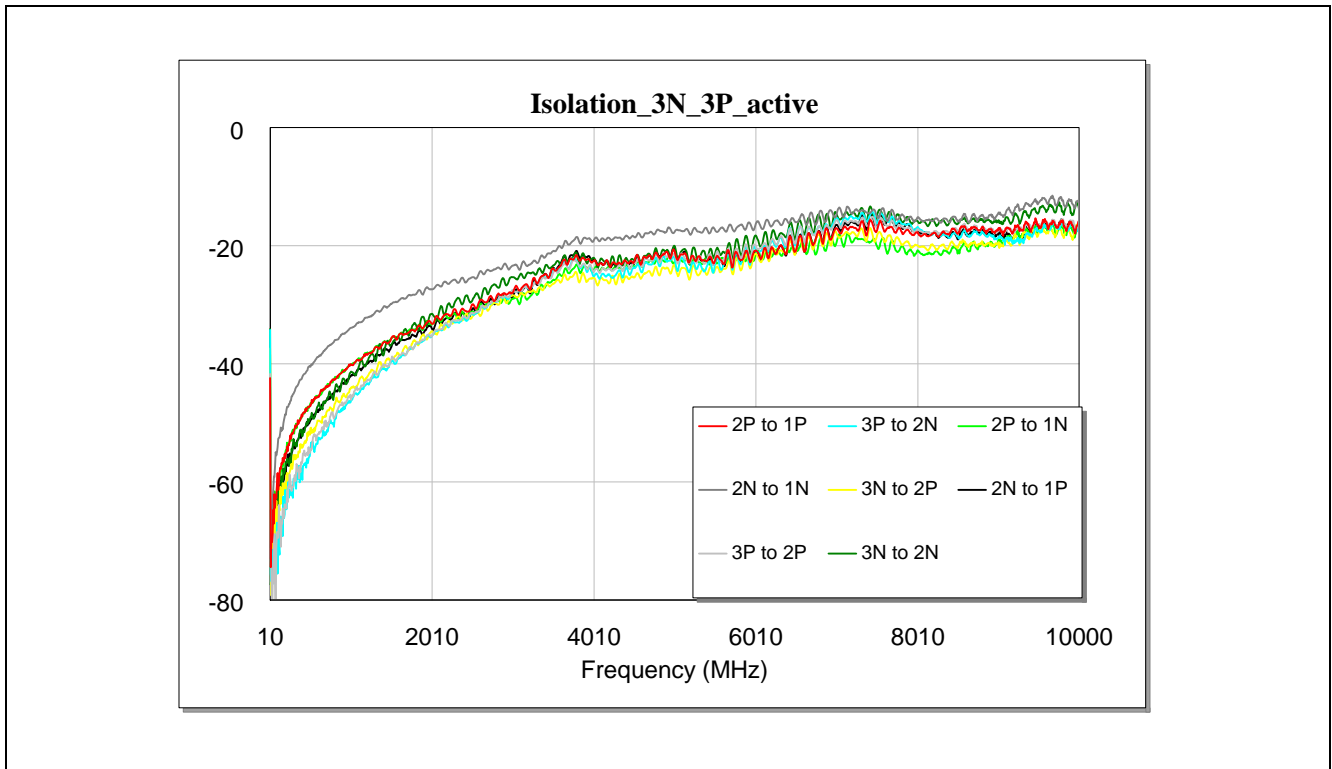


Figure 8 Isolation of Port 2 (2P/2N) by active Port 3 (3P/3N)

Table 8 Isolation of Port2 (2P/2N) bby active port 3 (3P/3N)

Port to port isolation	824	915	1000	1710	1910	2170	2690
2P → 1P	-36.3	-35.1	-34	-32.9	-29.1	-27.3	-24.2
2N → 1P	-42.5	-41.3	-41.1	-39.4	-35.6	-34.4	-31.5
2P → 1N	-45.1	-44.2	-43.6	-40.3	-34.5	-34.2	-31.2
2N → 1N	-42.5	-41.2	-40.1	-34.8	-33.7	-31.7	-29.5
2P → 3P	-36	-35	-34	-28.5	-27.9	-26.1	-24.1
2P → 3N	-48.5	-47	-45.3	-37.9	-35.9	-33.2	-30.2
2N → 3P	-49	-47.8	-46.5	-37.8	-36	-33.4	-30.3
2N → 3N	-46	-45.1	-44.3	-37.7	-35.1	-34.1	-30.9

4 Switching time

4.1 Measurement Specifications

Switching On Time: 50% Trigger signal to 90% RF Signal

Switching Off Time: 50% Trigger signal to 10% RF Signal

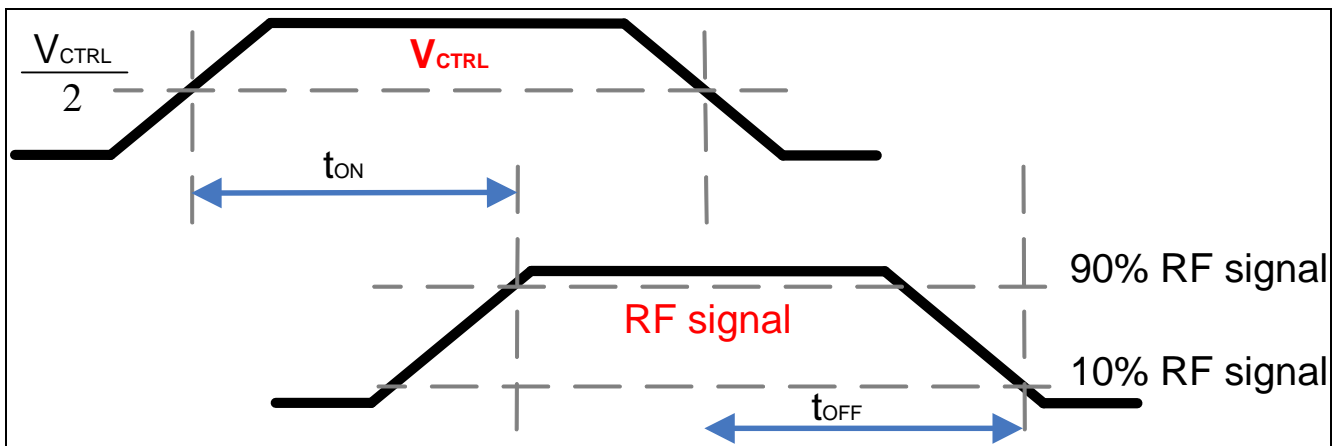


Figure 9 Switching Time

Rise time: 10% to 90% RF Signal

Fall time: 90% to 10% RF Signal

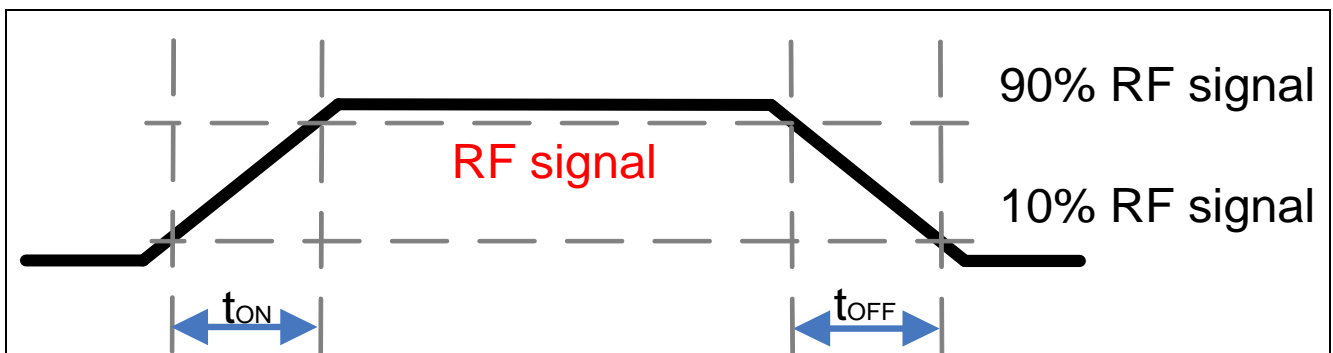


Figure 10 Rise/Fall Time

4.2 Measurement Setup

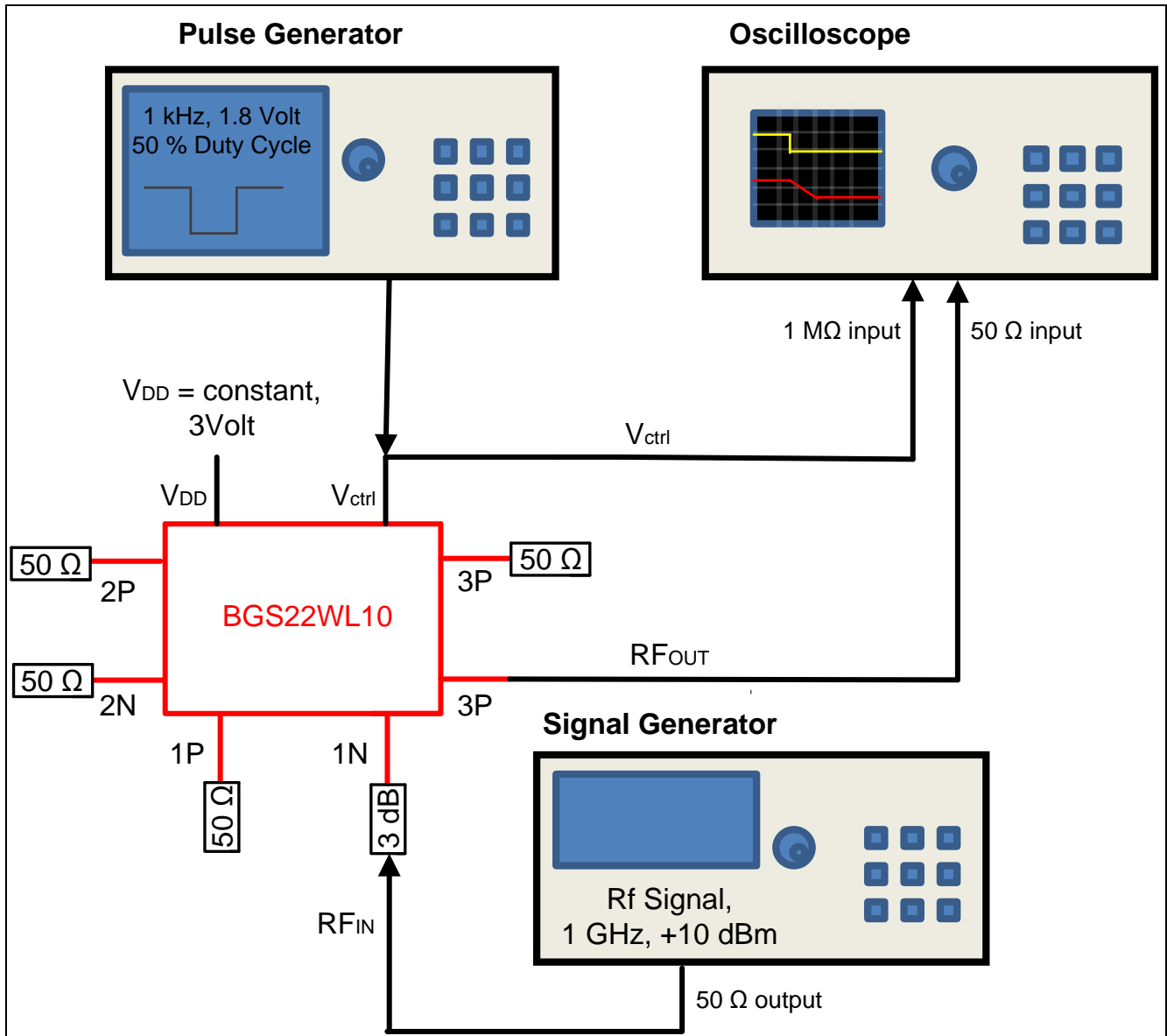


Figure 11 Switching Time Measurement Setup

The switching Time measurement setup consists of one pulse generator which generates a square wave with 50% duty cycle and an amplitude of 1.8 Volts, an oscilloscope which can detect the 1 GHz signal and the 1 kHz signal and one Signal generator which is set to an output signal of 1GHz with a power level 10 dBm.

If the oscilloscope can not detect the 1 GHz signal of the RF path, due to small bandwidth, it is possible to use a crystal oscillator in front of the oscilloscope (such a device detects any RF signal present at input and commutate that one) that the RF signal can be detected.

4.3 Measurement results

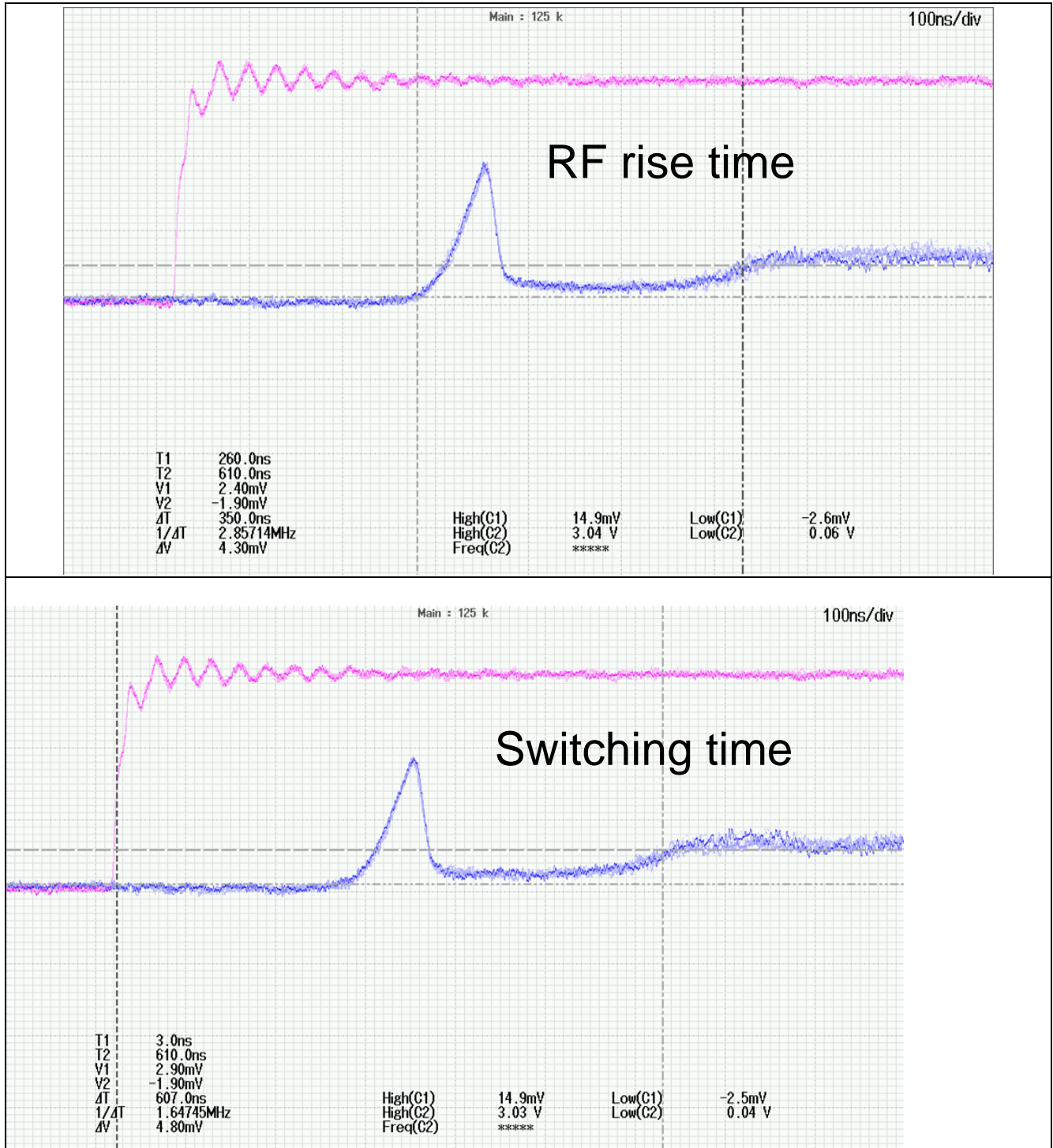


Figure 12 Switching Time of BGS22WL10

Table 9 Switching time measurement results of BGS22WL10

BGS22WL10	RF rise time (ns)	Switching time (ns)
	350	607

5 Intermodulation

5.1 Test conditions

Another very important parameter of a RF switch is the large signal capability. One of the possible intermodulation scenarios is shown in **Figure 13**. The transmission (Tx) signal from the main antenna is coupled into the diversity antenna with high power. This signal (20 dBm) and a received Jammer signal (-15 dBm) are entering the switch. Thank to the specified application for the BGS22WL10 in between the filters and the Transceiver, the Tx signal from the main antenna loose until arriving at the switch input mostly 5 to 10 or more dB, depending of the filter and pcb structure of the RF frontend. The IMD products are measured with a Tx of 20dBm, which is corresponding to the IMD spec of a main antenna diversity switch like Infineons BGSF110GN. Therefore, the measured IMD products will be extremely better in the specified application circuit within the filters and transceiver as showed in the measurement results below.

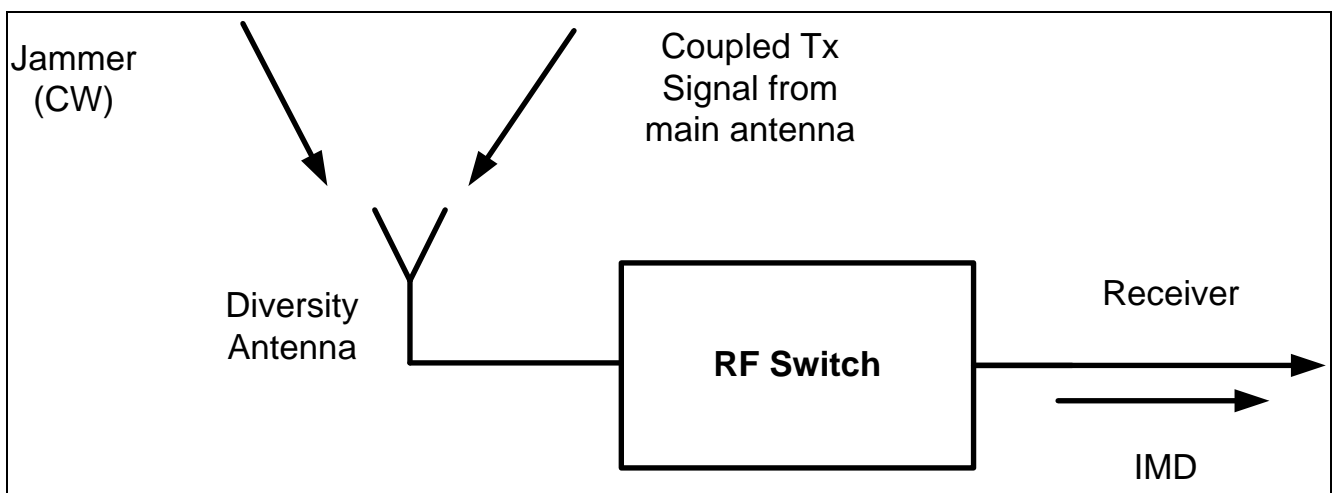


Figure 13 Block diagram of RF Switch intermodulation

Special combinations of TX and Jammer signal are producing intermodulation products 2nd and 3rd order, which fall in the RX band and disturb the wanted RX signal.

In **Table 10** frequencies for 3 bands and the linearity specifications for an undisturbed communication are given.

Table 10 Test conditions and specifications of IMD measurements

Test Conditions (Tx = +20dBm, BI = -15dBm, freq.in MHz, @25°C)						Linearity Specification			
Band	Tx Freq.	Rx Freq.	IMD2 Low Jammer 1	IMD3 Jammer 2	IMD2 High Jammer 3	IM2 (dBm)	IIP2 (dBm)	IM3 (dBm)	IIP3 (dBm)
850	836.5	881.5	45	791.5	1718	-105	110	-105	65
1900	1880	1960	80	1800	3840	-105	110	-105	65
2100	1950	2140	190	1760	4090	-105	110	-105	65

5.2 Measurement Setup

The test setup for the IMD measurements has to provide a very high isolation between RX and TX signals. As an example the test set-up and the results for the high band are shown (Figure 14 and Table 11).

For the RX / TX separation a professional duplexer with 80 dB isolation is used.

In Table 12 the results for Low band are given.

For each distortion scenario there is a min and a max value given. This variation is caused by a phase shifter connected between switch and duplexer. In the test set-up the phase shifter represents a no ideal matching of the switch to 50 Ohm.

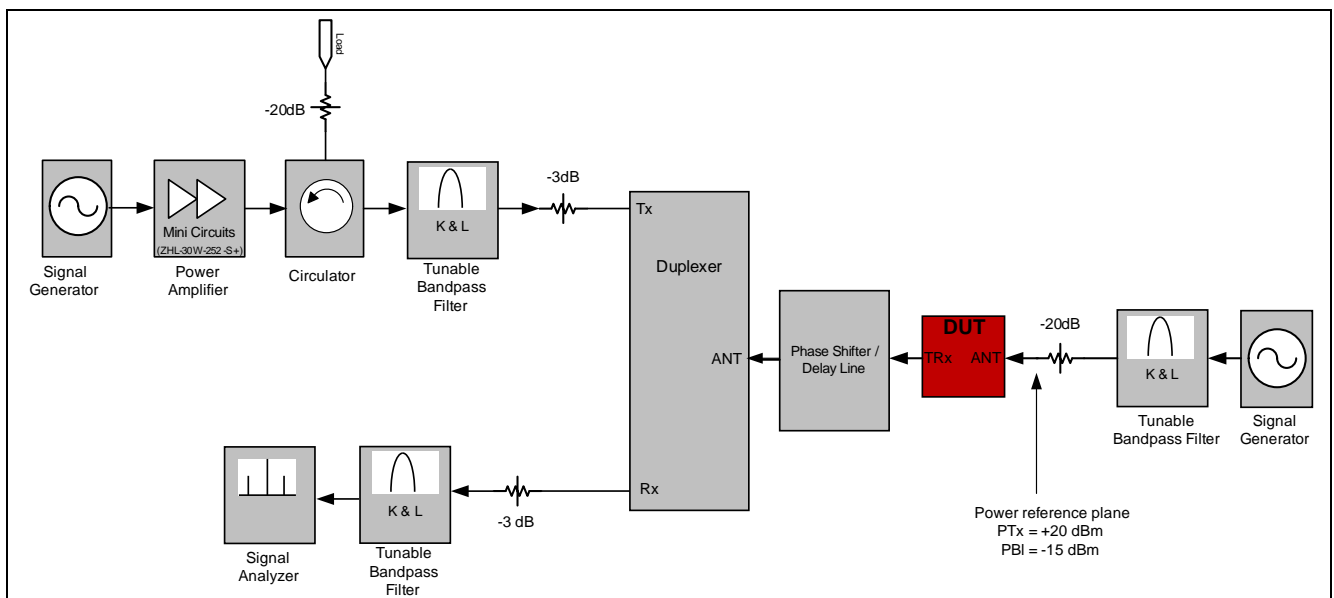


Figure 14 Test set-up for IMD Measurements

5.3 Measurement results

Table 11 IMD products of Band I

IMD Band 1	1P → 2P		1N → 2N		1P → 3P		1N → 3N	
	Min	Max	Min	Max	Min	Max	Min	Max
IMD2Low (fblocker = 190 MHz)	-116.72	-109.12	-117.71	-109.40	-118.60	-110.42	-118.89	-111.11
IMD2High (fblocker = 4090 MHz)	-118.37	-114.48	-115.80	-113.08	-118.23	-115.11	-119.19	-115.91
IMD3 (fblocker = 1760 MHz)	-123.37	-117.75	-123.00	-117.54	-122.55	-117.68	-123.19	-116.54

Table 12 IMD products of Band V

IMD Band 5	1P → 2P		1N → 2N		1P → 3P		1N → 3N	
	Min	Max	Min	Max	Min	Max	Min	Max
IMD2Low (fblocker = 45 MHz)	-107.69	-96.55	-108.80	-97.42	-108.59	-97.75	-107.62	-96.32
IMD2High (fblocker = 1718 MHz)	-113.11	-108.38	-112.34	-109.11	-112.65	-108.11	-113.55	-109.56
IMD3 (fblocker = 791.5 MHz)	-112.88	-108.46	-111.70	-107.97	112.86	-108.50	-113.62	-108.74

6 Harmonic Generation

6.1 Measurement setup

Harmonic generation is another important parameter for the characterization of a RF switch. RF switches have in such a Differential Band select Switching application to deal with high RF levels, up to 24 dBm. With this high RF power at the input of the switch harmonics are generated. This harmonics (2nd and 3rd) can disturb the other reception bands or cause distortion in other RF applications (GPS, WLAN) within the mobile phone.

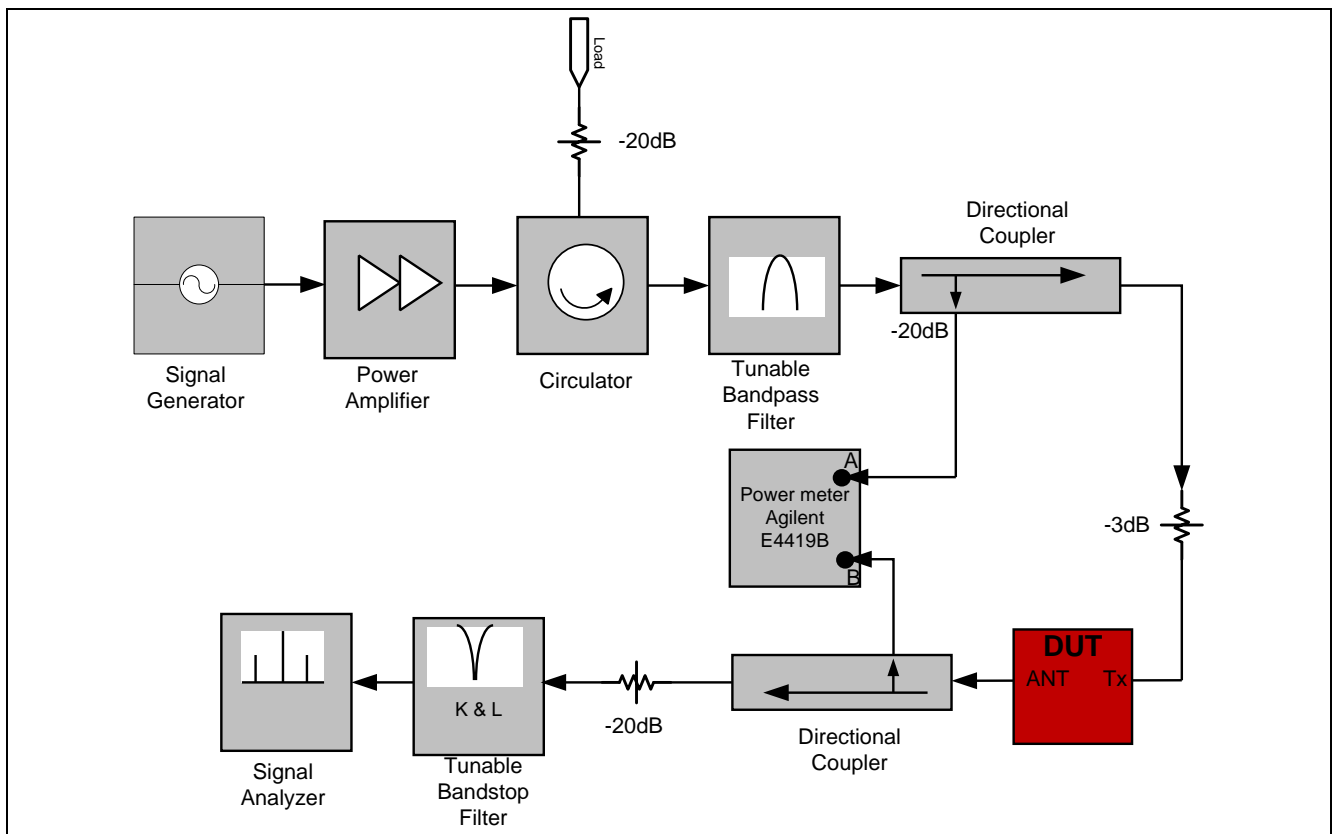


Figure 15 Set-up for harmonics measurement

The results for the harmonic generation at 830 MHz are shown in Figure 16 (2nd harmonic) and Figure 17 (3rd harmonic) for all RF ports.

At the x-axis the input power is plotted and at the y-axis the generated harmonics in dBm.

6.2 Measurement results

6.2.1 Low Band (824 MHz)

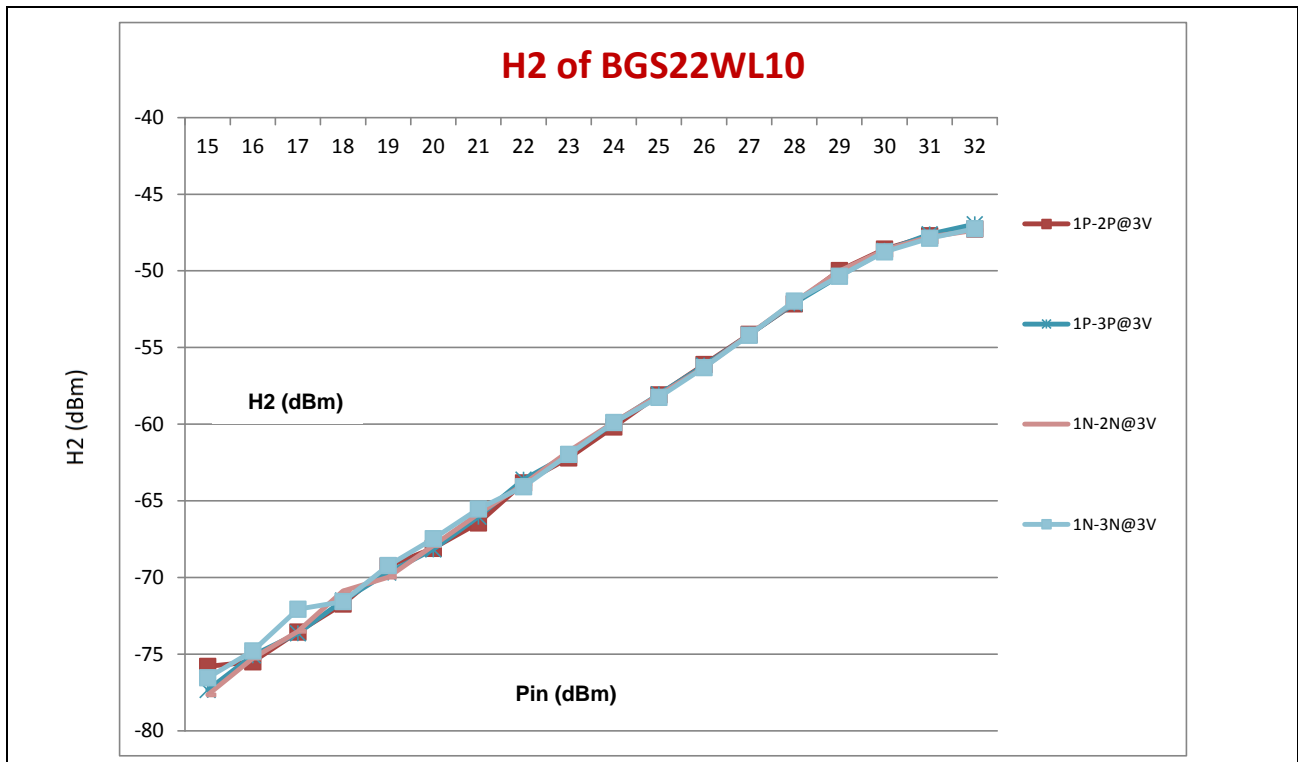


Figure 16 2nd harmonic at $f_c=824$ MHz

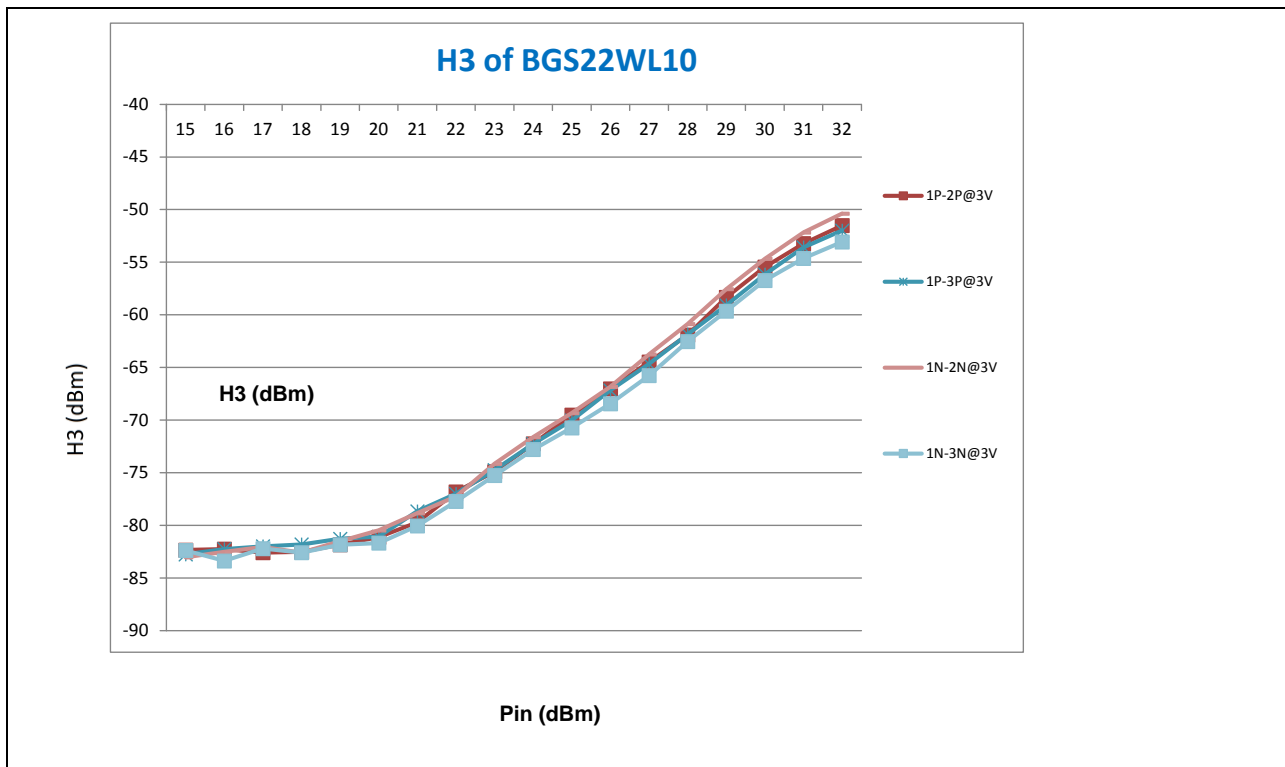


Figure 17 3rd harmonic at $f_c=824$ MHz

6.2.2 High Band (1800 MHz)

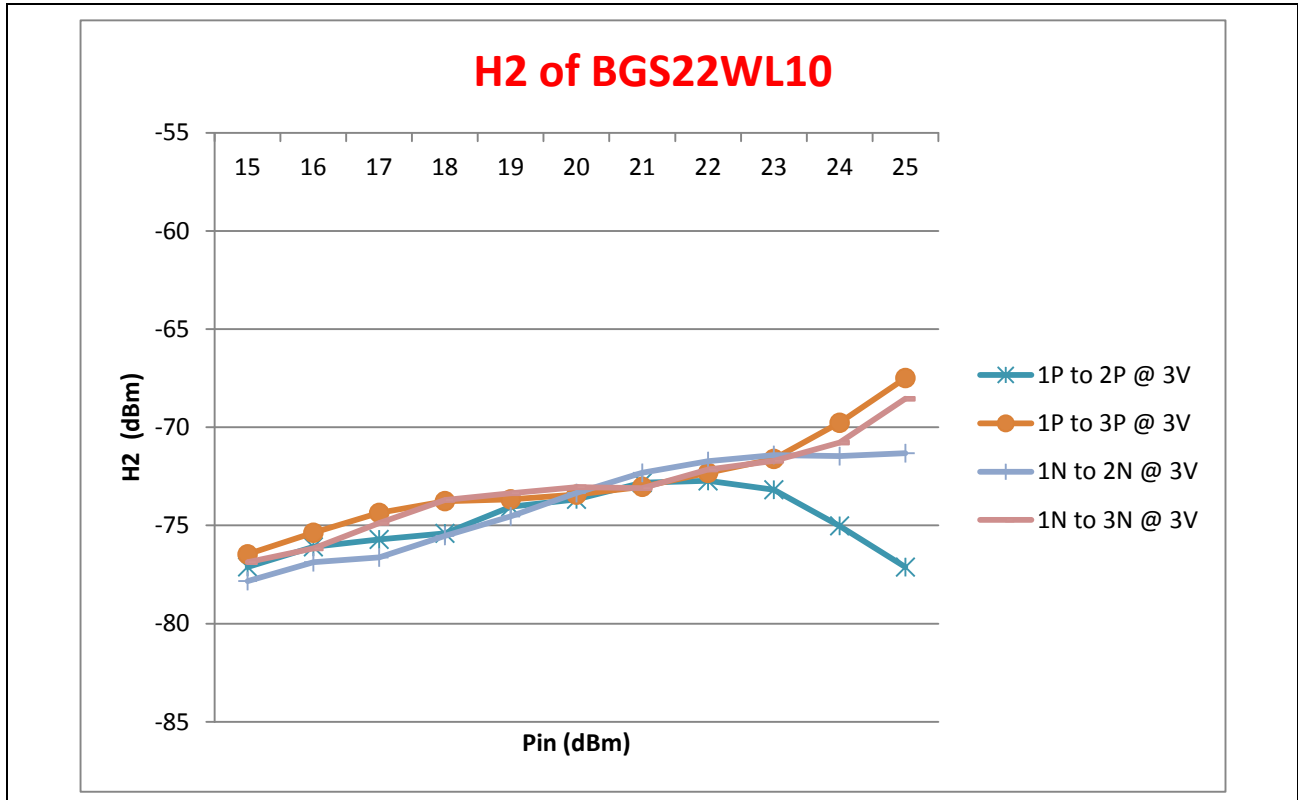


Figure 18 2nd harmonic at f_c=1800 MHz

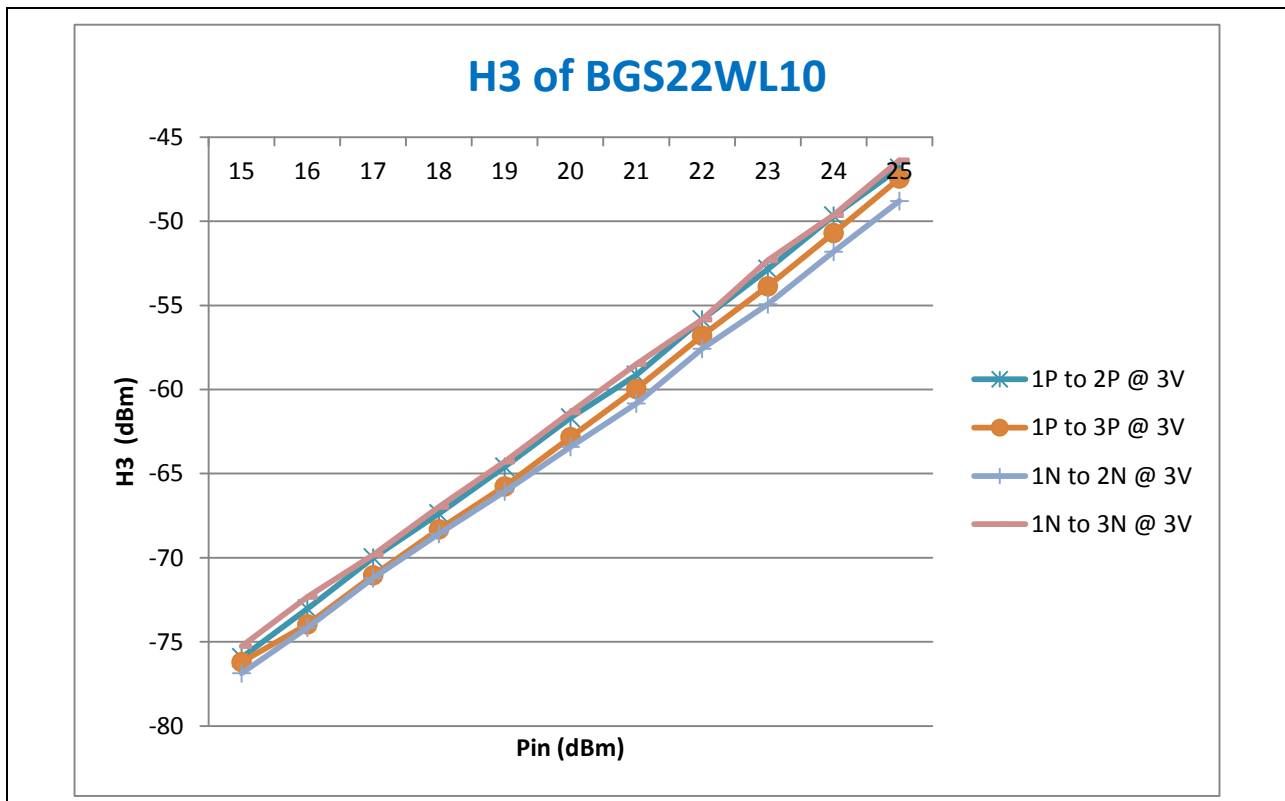


Figure 19 3rd harmonic at f_c=1800 MHz

7 Power Compression Measurements

To judge the large signal capability the power compression is a usual measurement tool. The input power is increase and at the output the power is measured. At a certain point the output power could not follow the input and the switch compresses the RF signal. In the diagram below ([Figure 20](#)) the IL is plotted versus the injected input power. The input power can be increased to 29 dBm and there is no compression visible of the RF port.

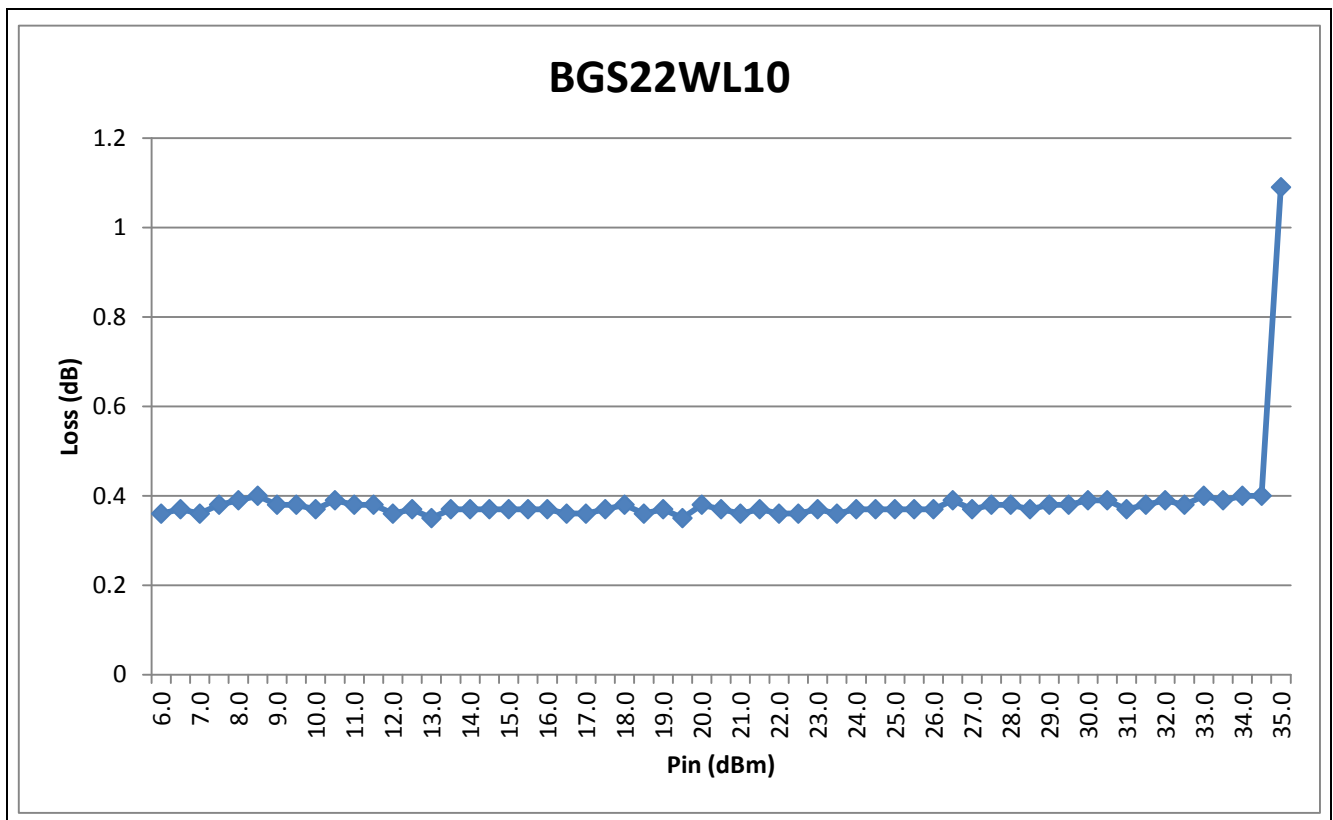


Figure 20 Power Compression Measurement Results at $f_c=824$ MHz

The measurements are done on Large Signal measurement setup which is not calibrated for Insertion Loss with high precision. So the values here may differ with the actual IL values earlier in this report.

8 Application Board and Measurement description

8.1 Application board

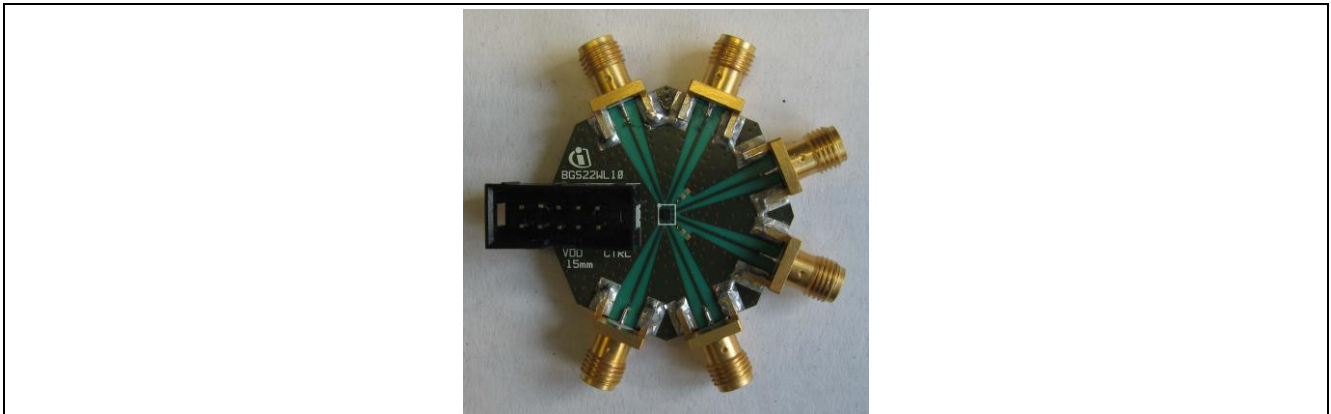


Figure 21 BGS22WL10 application board

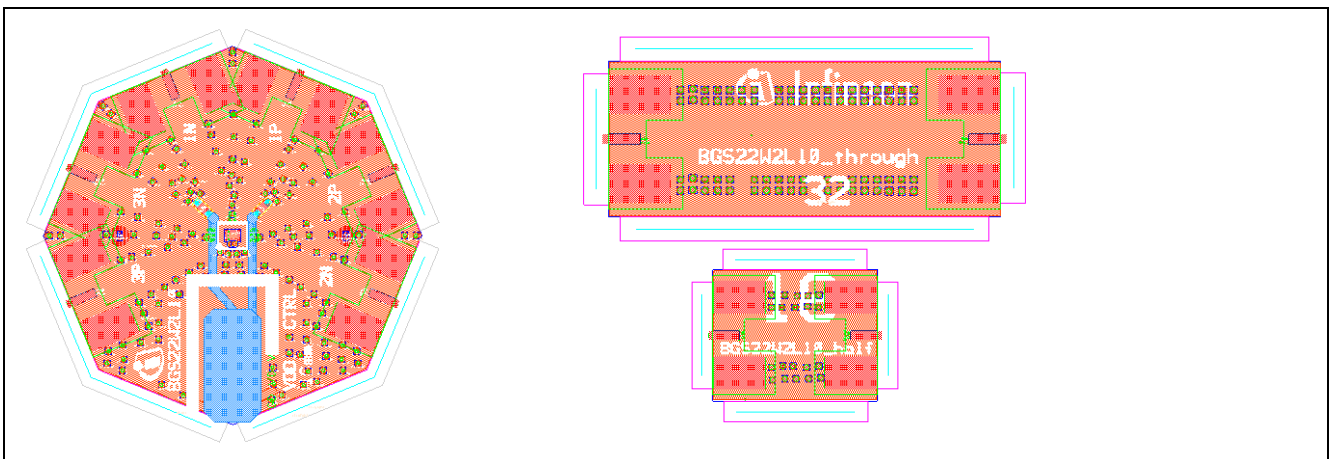


Figure 22 Layout of the application board and deembedding kit

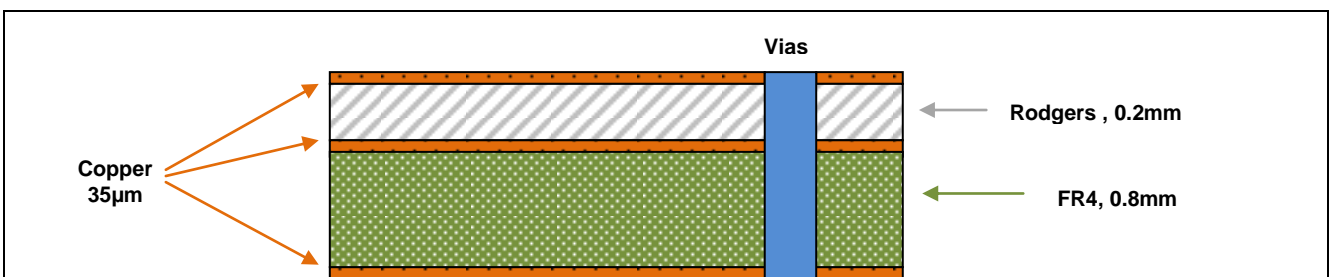


Figure 23 PCB layer information

8.2 Measurement description and deembedding

Below is a picture of the evaluation board used for the measurements (Figure 22). The board is designed in the way that all connecting 50 Ohm lines have the same length.

To get correct called “device level” measurement values for the insertion loss of the BGS22WL10 all influences and losses of the evaluation board, lines and connectors have to be eliminated. Therefore a separate de-embedding board, representing the line length is necessary.

After full port calibration of the network analyzer (NWA) a deembedding has to be done in several steps:

- Attach empty SMA connector (with cutted RF line, [Figure 24](#)) at any port of the measurements setup and perform “open” port extension for that one. Turn port extensions on.
- Connect the “half” de-embedding board ([Figure 22](#), smallest board) between the the port where one of the two RFin port (1P/1N) of the BGS22WL10 will be connected and the port with the mated port extension, store this as a S-parameter (s2p) file.
- Turn all port extention off.
- Load the stored s-parameter file as de-embedding on all used NWA ports
- Check insertion loss with the de-embedding through board ([Figure 22](#) right upper board)

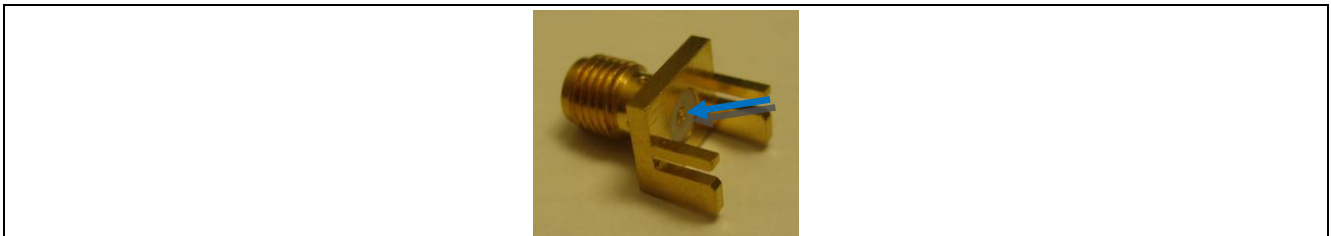


Figure 24 SMA connector for deembedding procedure

If the check of the deembedding shows an insertion loss of the through about +- 0.4 dB (depending on the measurement setup accuracy, e.g. NWA) then the Device itself can be measured.

Author

André Dewai, Application Engineer of the Business Unit "RF and Protection Devices"

Ralph Kuhn, Senior Staff Application Engineer of the Business Unit "RF and Protection Devices"

